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Details

Product Status	Obsolete
Core Processor	C166SV2
Core Size	16-Bit
Speed	80MHz
Connectivity	CANbus, EBI/EMI, I ² C, LINbus, SPI, SSC, UART/USART, USI
Peripherals	I ² S, POR, PWM, WDT
Number of I/O	76
Program Memory Size	192KB (192K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP Exposed Pad
Supplier Device Package	PG-LQFP-100-8
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/sak-xe164fm-24f80l-aa

XE164xM

Revision History: V2.1, 2011-07

Previous Version(s):

V2.0, 2009-03

V1.3, 2008-11

V1.2, 2008-09

V1.1, 2008-06 Preliminary

V1.0, 2008-06 (Intermediate version)

Page	Subjects (major changes since last revisions)
39	ID registers added
86	ADC capacitances corrected (typ. vs. max.)
90	Conditions relaxed for Δf_{INT} Range for f_{WU} adapted according to PCN 2010-013-A Added startup time from power-on t_{SPO}
127	Quality declarations added

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1.2 Definition of Feature Variants

The XE164xM types are offered with several Flash memory sizes. [Table 2](#) describes the location of the available memory areas for each Flash memory size.

Table 2 Flash Memory Allocation

Total Flash Size	Flash Area A ¹⁾	Flash Area B	Flash Area C
576 Kbytes	C0'0000 _H ... C0'FFFF _H	C1'0000 _H ... C7'FFFF _H	CC'0000 _H ... CC'FFFF _H
384 Kbytes	C0'0000 _H ... C0'FFFF _H	C1'0000 _H ... C4'FFFF _H	CC'0000 _H ... CC'FFFF _H
192 Kbytes	C0'0000 _H ... C0'FFFF _H	C1'0000 _H ... C1'FFFF _H	CC'0000 _H ... CC'FFFF _H

1) The uppermost 4-Kbyte sector of the first Flash segment is reserved for internal use (C0'F000_H to C0'FFFF_H).

Table 3 Flash Memory Module Allocation (in Kbytes)

Total Flash Size	Flash 0 ¹⁾	Flash 1	Flash 2	Flash 3
576 Kbytes	256	256	---	64
384 Kbytes	256	64	---	64
192 Kbytes	128	---	---	64

1) The uppermost 4-Kbyte sector of the first Flash segment is reserved for internal use (C0'F000_H to C0'FFFF_H).

The XE164xM types are offered with different interface options. [Table 4](#) lists the available channels for each option.

Table 4 Interface Channel Association

Total Number	Available Channels
11 ADC0 channels	CH0, CH2 ... CH5, CH8 ... CH11, CH13, CH15
6 ADC0 channels	CH0, CH2 ... CH5, CH8
5 ADC1 channels	CH0, CH2, CH4, CH5, CH6 (overlay: CH8 ... CH11)
4 CAN nodes	CAN0, CAN1, CAN2, CAN3 128 message objects
2 CAN nodes	CAN0, CAN1 128 message objects
6 serial channels	U0C0, U0C1, U1C0, U1C1, U2C0, U2C1
4 serial channels	U0C0, U0C1, U1C0, U1C1

2.1 Pin Configuration and Definition

The pins of the XE164xM are described in detail in [Table 5](#), which includes all alternate functions. For further explanations please refer to the footnotes at the end of the table. The following figure summarizes all pins, showing their locations on the four sides of the package.

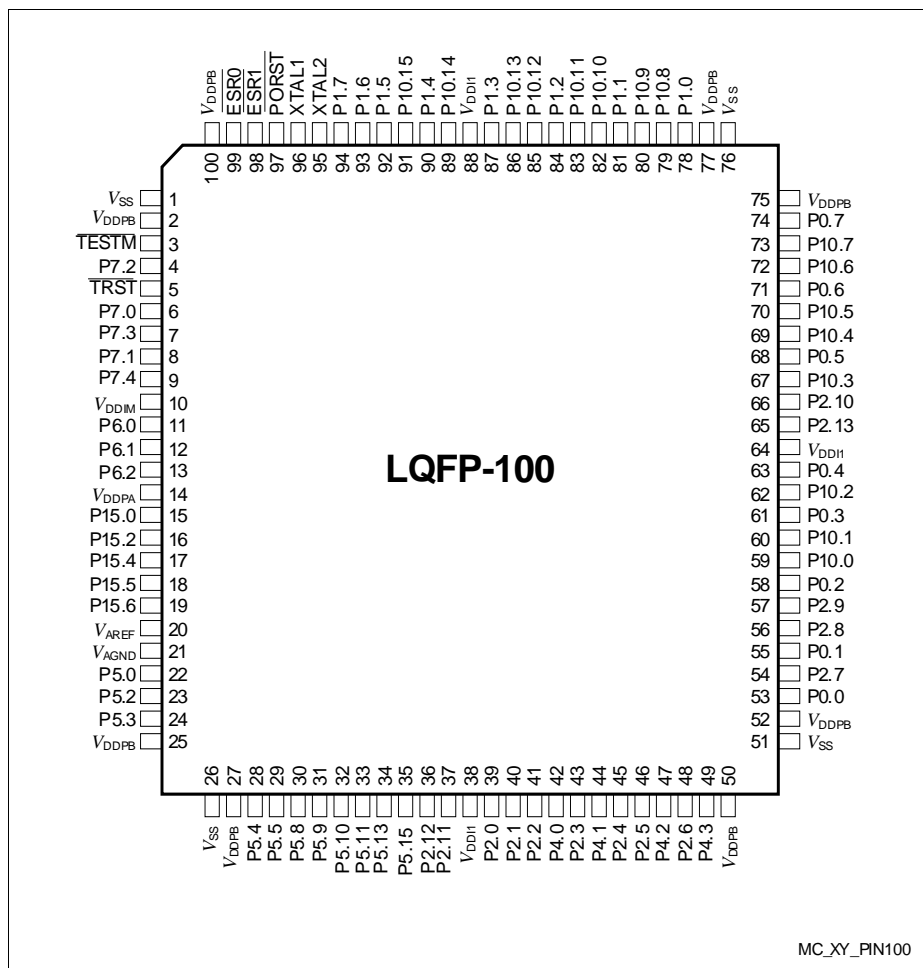


Figure 3 XE164xM Pin Configuration (top view)

Key to Pin Definitions

- **Ctrl.:** The output signal for a port pin is selected by bit field PC in the associated register Px_IOCry. Output O0 is selected by setting the respective bit field PC to 1x00_B, output O1 is selected by 1x01_B, etc.
 Output signal OH is controlled by hardware.
- **Type:** Indicates the pad type and its power supply domain (A, B, M, 1).
 - St: Standard pad
 - Sp: Special pad e.g. XTALx
 - DP: Double pad - can be used as standard or high speed pad
 - In: Input only pad
 - PS: Power supply pad

Table 5 Pin Definitions and Functions

Pin	Symbol	Ctrl.	Type	Function
3	$\overline{\text{TESTM}}$	I	In/B	Testmode Enable Enables factory test modes, must be held HIGH for normal operation (connect to V_{DDPB}). An internal pull-up device will hold this pin high when nothing is driving it.
4	P7.2	O0 / I	St/B	Bit 2 of Port 7, General Purpose Input/Output
	EMUX0	O1	St/B	External Analog MUX Control Output 0 (ADC1)
	CCU62_CCP OS0A	I	St/B	CCU62 Position Input 0
	TDI_C	IH	St/B	JTAG Test Data Input If JTAG pos. C is selected during start-up, an internal pull-up device will hold this pin high when nothing is driving it.
5	$\overline{\text{TRST}}$	I	In/B	Test-System Reset Input For normal system operation, pin $\overline{\text{TRST}}$ should be held low. A high level at this pin at the rising edge of $\overline{\text{PORST}}$ activates the XE164xM's debug system. In this case, pin $\overline{\text{TRST}}$ must be driven low once to reset the debug system. An internal pull-down device will hold this pin low when nothing is driving it.

Table 5 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
33	P5.11	I	In/A	Bit 11 of Port 5, General Purpose Input
	ADC0_CH11	I	In/A	Analog Input Channel 11 for ADC0
	ADC1_CH11	I	In/A	Analog Input Channel 11 for ADC1
34	P5.13	I	In/A	Bit 13 of Port 5, General Purpose Input
	ADC0_CH13	I	In/A	Analog Input Channel 13 for ADC0
35	P5.15	I	In/A	Bit 15 of Port 5, General Purpose Input
	ADC0_CH15	I	In/A	Analog Input Channel 15 for ADC0
	RxDC2F	I	In/A	CAN Node 2 Receive Data Input
36	P2.12	O0 / I	St/B	Bit 12 of Port 2, General Purpose Input/Output
	U0C0_SELO 4	O1	St/B	USIC0 Channel 0 Select/Control 4 Output
	U0C1_SELO 3	O2	St/B	USIC0 Channel 1 Select/Control 3 Output
	TXDC2	O3	St/B	CAN Node 2 Transmit Data Output
	READY	IH	St/B	External Bus Interface READY Input
37	P2.11	O0 / I	St/B	Bit 11 of Port 2, General Purpose Input/Output
	U0C0_SELO 2	O1	St/B	USIC0 Channel 0 Select/Control 2 Output
	U0C1_SELO 2	O2	St/B	USIC0 Channel 1 Select/Control 2 Output
	BHE/WRH	OH	St/B	External Bus Interf. High-Byte Control Output Can operate either as Byte High Enable (BHE) or as Write strobe for High Byte (WRH).
39	P2.0	O0 / I	St/B	Bit 0 of Port 2, General Purpose Input/Output
	AD13	OH / IH	St/B	External Bus Interface Address/Data Line 13
	RxDC0C	I	St/B	CAN Node 0 Receive Data Input
	T5INB	I	St/B	GPT12E Timer T5 Count/Gate Input

Table 5 Pin Definitions and Functions (cont'd)

Pin	Symbol	Ctrl.	Type	Function
84	P1.2	O0 / I	St/B	Bit 2 of Port 1, General Purpose Input/Output
	CCU62_CC62	O1	St/B	CCU62 Channel 2 Output
	U1C0_SELO6	O2	St/B	USIC1 Channel 0 Select/Control 6 Output
	U2C1_SCLKOUT	O3	St/B	USIC2 Channel 1 Shift Clock Output
	A10	OH	St/B	External Bus Interface Address Line 10
	ESR1_4	I	St/B	ESR1 Trigger Input 4
	CCU61_T12HRB	I	St/B	External Run Control Input for T12 of CCU61
	CCU62_CC62INA	I	St/B	CCU62 Channel 2 Input
	U2C1_DX0D	I	St/B	USIC2 Channel 1 Shift Data Input
	U2C1_DX1C	I	St/B	USIC2 Channel 1 Shift Clock Input
85	P10.12	O0 / I	St/B	Bit 12 of Port 10, General Purpose Input/Output
	U1C0_DOUT	O1	St/B	USIC1 Channel 0 Shift Data Output
	TxDC2	O2	St/B	CAN Node 2 Transmit Data Output
	TDO_B	OH / IH	St/B	JTAG Test Data Output / DAP1 Input/Output If DAP pos. 1 is selected during start-up, an internal pull-down device will hold this pin low when nothing is driving it.
	AD12	OH / IH	St/B	External Bus Interface Address/Data Line 12
	U1C0_DX0C	I	St/B	USIC1 Channel 0 Shift Data Input
	U1C0_DX1E	I	St/B	USIC1 Channel 0 Shift Clock Input

3.3 Central Processing Unit (CPU)

The core of the CPU consists of a 5-stage execution pipeline with a 2-stage instruction-fetch pipeline, a 16-bit arithmetic and logic unit (ALU), a 32-bit/40-bit multiply and accumulate unit (MAC), a register-file providing three register banks, and dedicated SFRs. The ALU features a multiply-and-divide unit, a bit-mask generator, and a barrel shifter.

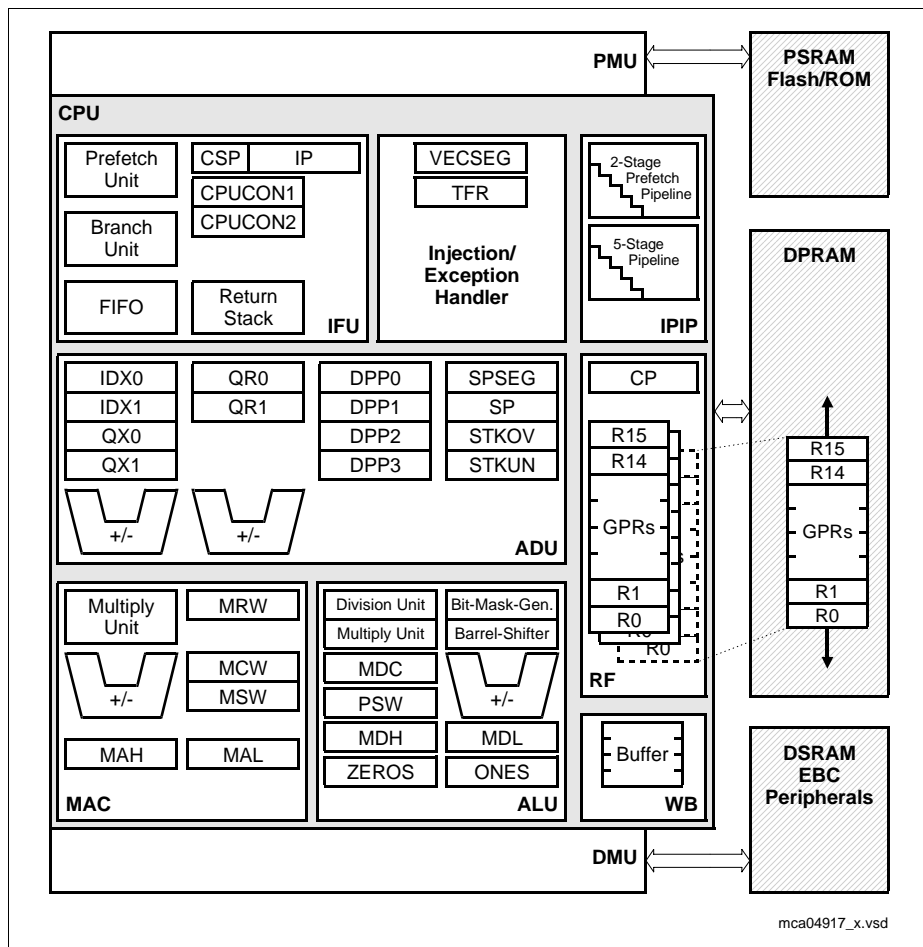


Figure 5 CPU Block Diagram

Functional Description

With this hardware most XE164xM instructions are executed in a single machine cycle of 12.5 ns with an 80-MHz CPU clock. For example, shift and rotate instructions are always processed during one machine cycle, no matter how many bits are shifted. Also, multiplication and most MAC instructions execute in one cycle. All multiple-cycle instructions have been optimized so that they can be executed very fast; for example, a 32-/16-bit division is started within 4 cycles while the remaining cycles are executed in the background. Another pipeline optimization, the branch target prediction, eliminates the execution time of branch instructions if the prediction was correct.

The CPU has a register context consisting of up to three register banks with 16 word-wide GPRs each at its disposal. One of these register banks is physically allocated within the on-chip DPRAM area. A Context Pointer (CP) register determines the base address of the active register bank accessed by the CPU at any time. The number of these register bank copies is only restricted by the available internal RAM space. For easy parameter passing, a register bank may overlap others.

A system stack of up to 32 Kwords is provided for storage of temporary data. The system stack can be allocated to any location within the address space (preferably in the on-chip RAM area); it is accessed by the CPU with the stack pointer (SP) register. Two separate SFRs, STKOV and STKUN, are implicitly compared with the stack pointer value during each stack access to detect stack overflow or underflow.

The high performance of the CPU hardware implementation can be best utilized by the programmer with the highly efficient XE164xM instruction set. This includes the following instruction classes:

- Standard Arithmetic Instructions
- DSP-Oriented Arithmetic Instructions
- Logical Instructions
- Boolean Bit Manipulation Instructions
- Compare and Loop Control Instructions
- Shift and Rotate Instructions
- Prioritize Instruction
- Data Movement Instructions
- System Stack Instructions
- Jump and Call Instructions
- Return Instructions
- System Control Instructions
- Miscellaneous Instructions

The basic instruction length is either 2 or 4 bytes. Possible operand types are bits, bytes and words. A variety of direct, indirect or immediate addressing modes are provided to specify the required operands.

Functional Description

to a dedicated vector table location). The occurrence of a hardware trap is also indicated by a single bit in the trap flag register (TFR). Unless another higher-priority trap service is in progress, a hardware trap will interrupt any ongoing program execution. In turn, hardware trap services can normally not be interrupted by standard or PEC interrupts.

Depending on the package option up to 3 External Service Request (ESR) pins are provided. The ESR unit processes their input values and allows to implement user controlled trap functions (System Requests SR0 and SR1). In this way reset, wakeup and power control can be efficiently realized.

Software interrupts are supported by the 'TRAP' instruction in combination with an individual trap (interrupt) number. Alternatively to emulate an interrupt by software a program can trigger interrupt requests by writing the Interrupt Request (IR) bit of an interrupt control register.

3.7 On-Chip Debug Support (OCDS)

The On-Chip Debug Support system built into the XE164xM provides a broad range of debug and emulation features. User software running on the XE164xM can be debugged within the target system environment.

The OCDS is controlled by an external debugging device via the debug interface. This either consists of the 2-pin Device Access Port (DAP) or of the JTAG port conforming to IEEE-1149. The debug interface can be completed with an optional break interface.

The debugger controls the OCDS with a set of dedicated registers accessible via the debug interface (DAP or JTAG). In addition the OCDS system can be controlled by the CPU, e.g. by a monitor program. An injection interface allows the execution of OCDS-generated instructions by the CPU.

Multiple breakpoints can be triggered by on-chip hardware, by software, or by an external trigger input. Single stepping is supported, as is the injection of arbitrary instructions and read/write access to the complete internal address space. A breakpoint trigger can be answered with a CPU halt, a monitor call, a data transfer, or/and the activation of an external signal.

Tracing data can be obtained via the debug interface, or via the external bus interface for increased performance.

Tracing of program execution is supported by the XE166 Family emulation device.

The DAP interface uses two interface signals, the JTAG interface uses four interface signals, to communicate with external circuitry. The debug interface can be amended with two optional break lines.

3.8 Capture/Compare Unit (CAPCOM2)

The CAPCOM2 unit supports generation and control of timing sequences on up to 16 channels with a maximum resolution of one system clock cycle (eight cycles in staggered mode). The CAPCOM2 unit is typically used to handle high-speed I/O tasks such as pulse and waveform generation, pulse width modulation (PWM), digital to analog (D/A) conversion, software timing, or time recording with respect to external events.

Two 16-bit timers (T7/T8) with reload registers provide two independent time bases for the capture/compare register array.

The input clock for the timers is programmable to several prescaled values of the internal system clock, or may be derived from an overflow/underflow of timer T6 in module GPT2. This provides a wide range or variation for the timer period and resolution and allows precise adjustments to the application-specific requirements. In addition, an external count input allows event scheduling for the capture/compare registers relative to external events.

The capture/compare register array contains 16 dual purpose capture/compare registers, each of which may be individually allocated to either CAPCOM timer and programmed for capture or compare function.

All registers have each one port pin associated with it which serves as an input pin for triggering the capture function, or as an output pin to indicate the occurrence of a compare event.

When a capture/compare register has been selected for capture mode, the current contents of the allocated timer will be latched ('captured') into the capture/compare register in response to an external event at the port pin which is associated with this register. In addition, a specific interrupt request for this capture/compare register is generated. Either a positive, a negative, or both a positive and a negative external signal transition at the pin can be selected as the triggering event.

The contents of all registers which have been selected for one of the five compare modes are continuously compared with the contents of the allocated timers.

When a match occurs between the timer value and the value in a capture/compare register, specific actions will be taken based on the selected compare mode.

Table 8 Compare Modes

Compare Modes	Function
Mode 0	Interrupt-only compare mode; Several compare interrupts per timer period are possible
Mode 1	Pin toggles on each compare match; Several compare events per timer period are possible

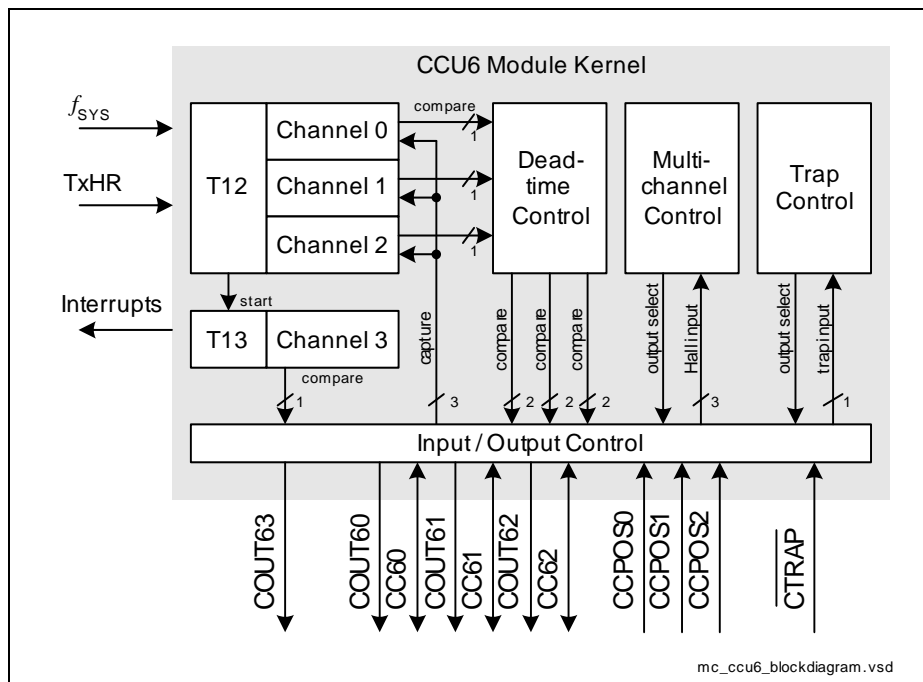


Figure 7 CCU6 Block Diagram

Timer T12 can work in capture and/or compare mode for its three channels. The modes can also be combined. Timer T13 can work in compare mode only. The multi-channel control unit generates output patterns that can be modulated by timer T12 and/or timer T13. The modulation sources can be selected and combined for signal modulation.

3.12 A/D Converters

For analog signal measurement, up to two 10-bit A/D converters (ADC0, ADC1) with 11 + 5 multiplexed input channels and a sample and hold circuit have been integrated on-chip. 4 inputs can be converted by both A/D converters. Conversions use the successive approximation method. The sample time (to charge the capacitors) and the conversion time are programmable so that they can be adjusted to the external circuit. The A/D converters can also operate in 8-bit conversion mode, further reducing the conversion time.

Several independent conversion result registers, selectable interrupt requests, and highly flexible conversion sequences provide a high degree of programmability to meet the application requirements. Both modules can be synchronized to allow parallel sampling of two input channels.

For applications that require more analog input channels, external analog multiplexers can be controlled automatically. For applications that require fewer analog input channels, the remaining channel inputs can be used as digital input port pins.

The A/D converters of the XE164xM support two types of request sources which can be triggered by several internal and external events.

- Parallel requests are activated at the same time and then executed in a predefined sequence.
- Queued requests are executed in a user-defined sequence.

In addition, the conversion of a specific channel can be inserted into a running sequence without disturbing that sequence. All requests are arbitrated according to the priority level assigned to them.

Data reduction features reduce the number of required CPU access operations allowing the precise evaluation of analog inputs (high conversion rate) even at a low CPU speed. Result data can be reduced by limit checking or accumulation of results.

The Peripheral Event Controller (PEC) can be used to control the A/D converters or to automatically store conversion results to a table in memory for later evaluation, without requiring the overhead of entering and exiting interrupt routines for each data transfer. Each A/D converter contains eight result registers which can be concatenated to build a result FIFO. Wait-for-read mode can be enabled for each result register to prevent the loss of conversion data.

In order to decouple analog inputs from digital noise and to avoid input trigger noise, those pins used for analog input can be disconnected from the digital input stages. This can be selected for each pin separately with the Port x Digital Input Disable registers.

The Auto-Power-Down feature of the A/D converters minimizes the power consumption when no conversion is in progress.

Broken wire detection for each channel and a multiplexer test mode provide information to verify the proper operation of the analog signal sources (e.g. a sensor system).

3.18 Parallel Ports

The XE164xM provides up to 76 I/O lines which are organized into 7 input/output ports and 2 input ports. All port lines are bit-addressable, and all input/output lines can be individually (bit-wise) configured via port control registers. This configuration selects the direction (input/output), push/pull or open-drain operation, activation of pull devices, and edge characteristics (shape) and driver characteristics (output current) of the port drivers. The I/O ports are true bidirectional ports which are switched to high impedance state when configured as inputs. During the internal reset, all port pins are configured as inputs without pull devices active.

All port lines have alternate input or output functions associated with them. These alternate functions can be programmed to be assigned to various port pins to support the best utilization for a given application. For this reason, certain functions appear several times in [Table 9](#).

All port lines that are not used for alternate functions may be used as general purpose I/O lines.

Table 9 Summary of the XE164xM's Ports

Port	Width	I/O	Connected Modules
P0	8	I/O	EBC (A7...A0), CCU6, USIC, CAN
P1	8	I/O	EBC (A15...A8), CCU6, USIC
P2	14	I/O	EBC (READY, $\overline{\text{BHE}}$, A23...A16, AD15...AD13, D15...D13), CAN, CC2, GPT12E, USIC, DAP/JTAG
P4	4	I/O	EBC ($\overline{\text{CS3}}$... $\overline{\text{CS0}}$), CC2, CAN, GPT12E, USIC
P5	11	I	Analog Inputs, CCU6, DAP/JTAG, GPT12E, CAN
P6	3	I/O	ADC, CAN, GPT12E
P7	5	I/O	CAN, GPT12E, SCU, DAP/JTAG, CCU6, ADC, USIC
P10	16	I/O	EBC (ALE, $\overline{\text{RD}}$, $\overline{\text{WR}}$, AD12...AD0, D12...D0), CCU6, USIC, DAP/JTAG, CAN
P15	5	I	Analog Inputs, GPT12E

Functional Description

Table 10 Instruction Set Summary (cont'd)

Mnemonic	Description	Bytes
ROL/ROR	Rotate left/right direct word GPR	2
ASHR	Arithmetic (sign bit) shift right direct word GPR	2
MOV(B)	Move word (byte) data	2 / 4
MOVBS/Z	Move byte operand to word op. with sign/zero extension	2 / 4
JMPA/I/R	Jump absolute/indirect/relative if condition is met	4
JMPS	Jump absolute to a code segment	4
JB(C)	Jump relative if direct bit is set (and clear bit)	4
JNB(S)	Jump relative if direct bit is not set (and set bit)	4
CALLA/I/R	Call absolute/indirect/relative subroutine if condition is met	4
CALLS	Call absolute subroutine in any code segment	4
PCALL	Push direct word register onto system stack and call absolute subroutine	4
TRAP	Call interrupt service routine via immediate trap number	2
PUSH/POP	Push/pop direct word register onto/from system stack	2
SCXT	Push direct word register onto system stack and update register with word operand	4
RET(P)	Return from intra-segment subroutine (and pop direct word register from system stack)	2
RETS	Return from inter-segment subroutine	2
RETI	Return from interrupt service subroutine	2
SBRK	Software Break	2
SRST	Software Reset	4
IDLE	Enter Idle Mode	4
PWRDN	Unused instruction ¹⁾	4
SRVWDT	Service Watchdog Timer	4
DISWDT/ENWDT	Disable/Enable Watchdog Timer	4
EINIT	End-of-Initialization Register Lock	4
ATOMIC	Begin ATOMIC sequence	2
EXTR	Begin EXTENDED Register sequence	2
EXTP(R)	Begin EXTENDED Page (and Register) sequence	2 / 4
EXTS(R)	Begin EXTENDED Segment (and Register) sequence	2 / 4

Electrical Parameters

Table 14 DC Characteristics for Lower Voltage Range (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Output Low Voltage ⁸⁾	$V_{OL\ CC}$	—	—	1.0	V	$I_{OL} \leq I_{OLmax}$
		—	—	0.4	V	$I_{OL} \leq I_{OLnom}$ ¹⁰⁾

- 1) Because each double bond pin is connected to two pads (standard pad and high-speed pad), it has twice the normal value. For a list of affected pins refer to the pin definitions table in chapter 2.
- 2) Not subject to production test - verified by design/characterization. Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It cannot suppress switching due to external system noise under all conditions.
- 3) If the input voltage exceeds the respective supply voltage due to ground bouncing ($V_{IN} < V_{SS}$) or supply ripple ($V_{IN} > V_{DDP}$), a certain amount of current may flow through the protection diodes. This current adds to the leakage current. An additional error current (I_{INJ}) will flow if an overload current flows through an adjacent pin. Please refer to the definition of the overload coupling factor K_{OV} .
- 4) The given values are worst-case values. In production test, this leakage current is only tested at 125 °C; other values are ensured by correlation. For derating, please refer to the following descriptions: Leakage derating depending on temperature (T_J = junction temperature [°C]): $I_{OZ} = 0.05 \times e^{(1.5 + 0.028 \times T_J)}$ [μA]. For example, at a temperature of 95 °C the resulting leakage current is 3.2 μA. Leakage derating depending on voltage level ($DV = V_{DDP} - V_{PIN}$ [V]): $I_{OZ} = I_{OZtempmax} - (1.6 \times DV)$ (μA). This voltage derating formula is an approximation which applies for maximum temperature.
- 5) Drive the indicated minimum current through this pin to change the default pin level driven by the enabled pull device: $V_{PIN} \leq V_{IL}$ for a pullup; $V_{PIN} \geq V_{IH}$ for a pulldown.
- 6) These values apply to the fixed pull-devices in dedicated pins and to the user-selectable pull-devices in general purpose IO pins.
- 7) Limit the current through this pin to the indicated value so that the enabled pull device can keep the default pin level: $V_{PIN} \geq V_{IH}$ for a pullup; $V_{PIN} \leq V_{IL}$ for a pulldown.
- 8) The maximum deliverable output current of a port driver depends on the selected output driver mode. This specification is not valid for outputs which are switched to open drain mode. In this case the respective output will float and the voltage is determined by the external circuit.
- 9) As a rule, with decreasing output current the output levels approach the respective supply level (VOL->VSS, VOH->VDDP). However, only the levels for nominal output currents are verified.
- 10) As a rule, with decreasing output current the output levels approach the respective supply level ($V_{OL} \rightarrow V_{SS}$, $V_{OH} \rightarrow V_{DDP}$). However, only the levels for nominal output currents are verified.

Electrical Parameters

Table 17 ADC Parameters (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Broken wire detection delay against V _{AGND} ²⁾	t_{BWG} CC	—	—	50	³⁾	
Broken wire detection delay against V _{AREF} ²⁾	t_{BWR} CC	—	—	50	⁴⁾	
Conversion time for 8-bit result ²⁾	t_{c8} CC	(11 + STC) × t_{ADCI} + 2 × t_{SYS}				
Conversion time for 10-bit result ²⁾	t_{c10} CC	(13 + STC) × t_{ADCI} + 2 × t_{SYS}				
Total Unadjusted Error	TUE CC	—	1	2	LSB ⁵⁾	
Wakeup time from analog powerdown, fast mode ²⁾	t_{WAF} CC	—	—	4	μs	
Wakeup time from analog powerdown, slow mode ²⁾	t_{WAS} CC	—	—	15	μs	
Analog reference ground	V _{AGND} SR	V _{SS} - 0.05	—	1.5	V	
Analog input voltage range	V _{AIN} SR	V _{AGND}	—	V _{AREF}	V ⁶⁾	
Analog reference voltage	V _{AREF} SR	V _{AGND} + 1.0	—	V _{DDPA} + 0.05	V ⁵⁾	

1) These parameter values cover the complete operating range. Under relaxed operating conditions (room temperature, nominal supply voltage) the typical values can be used for calculation.

2) This parameter includes the sample time (also the additional sample time specified by STC), the time to determine the digital result and the time to load the result register with the conversion result. Values for the basic clock t_{ADCI} depend on programming.

3) The broken wire detection delay against V_{AGND} is measured in numbers of consecutive precharge cycles at a conversion rate of not more than 500 μs. Result below 10% (66_H).

4) The broken wire detection delay against V_{AREF} is measured in numbers of consecutive precharge cycles at a conversion rate of not more than 10 μs. This function is influenced by leakage current, in particular at high temperature. Result above 80% (332_H).

5) TUE is tested at V_{AREF} = V_{DDPA} = 5.0 V, V_{AGND} = 0 V. It is verified by design for all other voltages within the defined voltage range. The specified TUE is valid only if the absolute sum of input overload currents on analog port pins (see I_{OV} specification) does not exceed 10 mA, and if V_{AREF} and V_{AGND} remain stable during the measurement time.

6) V_{AIN} may exceed V_{AGND} or V_{AREF} up to the absolute maximum ratings. However, the conversion result in these cases will be X000_H or X3FF_H, respectively.

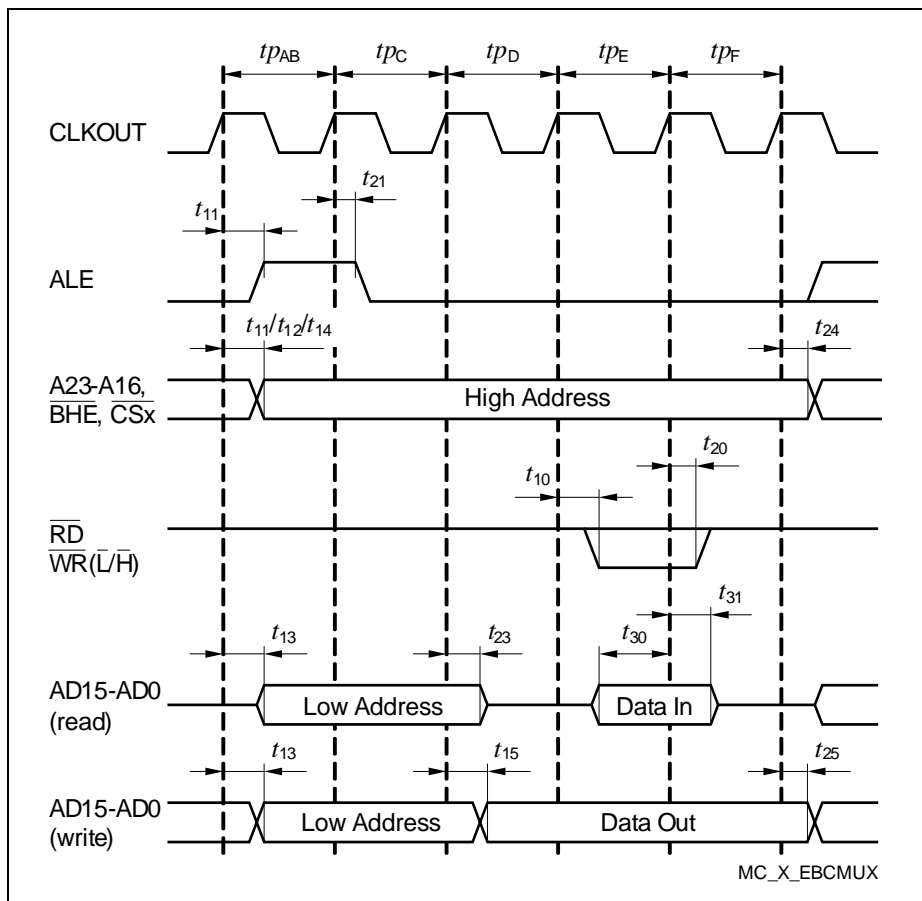


Figure 23 Multiplexed Bus Cycle

Electrical Parameters

Table 32 USIC SSC Master Mode Timing for Lower Voltage Range (cont'd)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Receive data input setup time to SCLKOUT receive edge	t_4 SR	40	—	—	ns	
Data input DX0 hold time from SCLKOUT receive edge	t_5 SR	-5	—	—	ns	

1) $t_{SYS} = 1 / f_{SYS}$

Table 33 USIC SSC Slave Mode Timing for Upper Voltage Range

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Select input DX2 setup to first clock input DX1 transmit edge ¹⁾	t_{10} SR	7	—	—	ns	
Select input DX2 hold after last clock input DX1 receive edge ¹⁾	t_{11} SR	7	—	—	ns	
Receive data input setup time to shift clock receive edge ¹⁾	t_{12} SR	7	—	—	ns	
Data input DX0 hold time from clock input DX1 receive edge ¹⁾	t_{13} SR	5	—	—	ns	
Data output DOUT valid time	t_{14} CC	7	—	33	ns	

1) These input timings are valid for asynchronous input signal handling of slave select input, shift clock input, and receive data input (bits DXnCR.DSEN = 0).

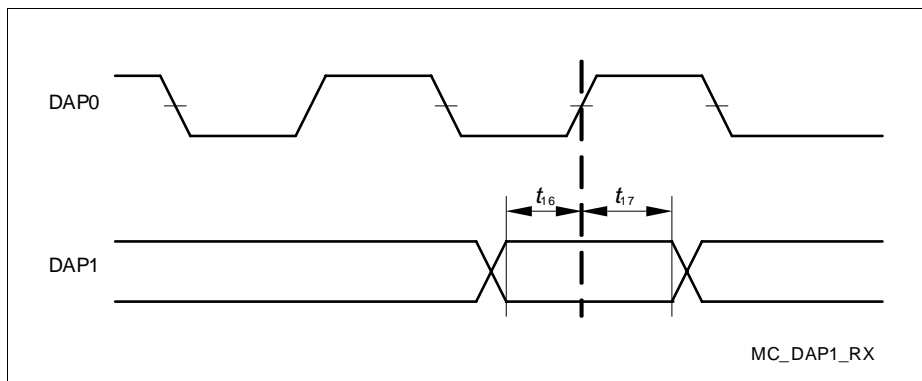


Figure 28 DAP Timing Host to Device

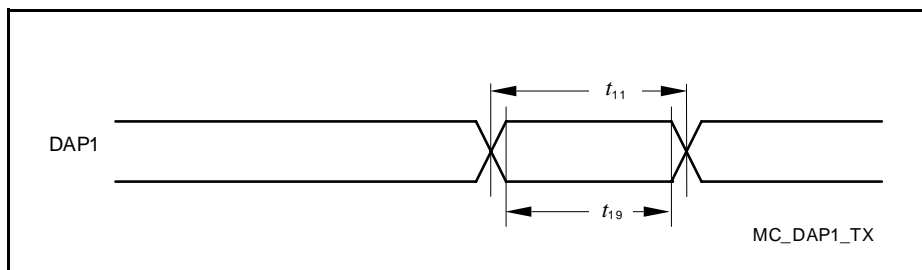


Figure 29 DAP Timing Device to Host

Note: The transmission timing is determined by the receiving debugger by evaluating the sync-request synchronization pattern telegram.

5 Package and Reliability

The XE166 Family devices use the package type PG-LQFP (Plastic Green - Low Profile Quad Flat Package). The following specifications must be regarded to ensure proper integration of the XE164xM in its target environment.

5.1 Packaging

These parameters specify the packaging rather than the silicon.

Table 39 Package Parameters (PG-LQFP-100-8)

Parameter	Symbol	Limit Values		Unit	Notes
		Min.	Max.		
Exposed Pad Dimension	$E_x \times E_y$	–	6.2×6.2	mm	–
Power Dissipation	P_{DISS}	–	1.0	W	–
Thermal resistance Junction-Ambient	$R_{\Theta JA}$	–	47	K/W	No thermal via ¹⁾
			29	K/W	4-layer, no pad ²⁾
			23	K/W	4-layer, pad ³⁾

1) Device mounted on a 2-layer JEDEC board (according to JESD 51-3) or a 4-layer board without thermal vias; exposed pad not soldered.

2) Device mounted on a 4-layer JEDEC board (according to JESD 51-7) with thermal vias; exposed pad not soldered.

3) Device mounted on a 4-layer JEDEC board (according to JESD 51-7) with thermal vias; exposed pad soldered to the board.

Note: To improve the EMC behavior, it is recommended to connect the exposed pad to the board ground, independent of the thermal requirements.

Board layout examples are given in an application note.

Package Compatibility Considerations

The XE164xM is a member of the XE166 Family of microcontrollers. It is also compatible to a certain extent with members of similar families or subfamilies.

Each package is optimized for the device it houses. Therefore, there may be slight differences between packages of the same pin-count but for different device types. In particular, the size of the Exposed Pad (if present) may vary.

If different device types are considered or planned for an application, it must be ensured that the board layout fits all packages under consideration.